



Click [here](#) for the 3D model.

Dimensions	
Chip Size	2220
L	5.9mm +/-0.4mm
W	5mm +/-0.4mm
T	1.4mm +/-0.15mm
B	0.6mm +/-0.35mm

Packaging Specifications	
Packaging	T&R, 330mm, Plastic Tape
Packaging Quantity	4000

General Information	
Series	KC-LINK Comm COG
Style	SMD Chip
Description	SMD, MLCC, Ultra-Stable, Low Loss, Class I
Features	Ultra-Stable, Low Loss, Class I
RoHS	Yes
Termination	Tin
Marking	No
AEC-Q200	No
Component Weight	190 mg
Shelf Life	78 Weeks
MSL	1

Specifications	
Capacitance	0.039 uF
Measurement Condition	1 kHz 1.0Vrms
Capacitance Tolerance	10%
Voltage DC	500 VDC
Dielectric Withstanding Voltage	750 VDC
Temperature Range	-55/+150°C
Temperature Coefficient	COG
Capacitance Change with Reference to +25°C and 0 VDC Applied (TCC)	30 ppm/C, 1kHz 1.0Vrms
Dissipation Factor	0.1% 1kHz 1.0Vrms
Aging Rate	0% Loss/Decade Hour
Insulation Resistance	25.641 GOhms